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Instability of Threshold Voltage under DC Drain Bias Stress in Pentacene-based Organic Thin Film Transistors

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1. Introduction

Organic thin-film transistors (OTFTs) have attracted much attention due to their low-temperature and low-cost fabrication process. Their possible applications are flat-panel displays, electronic papers, radio-frequency identification tags (RFIDs) etc [1-3]. OTFT performance has been significantly improved in the last few years and is comparable to that of the amorphous silicon thin-film transistors (α -TFTs) [4,]. However, the performance stability of OTFT is the key issue for mass production and commercialization. It has been reported that the performance degradation of OTFT includes hydroxyl radicals trapped at grain boundary [5,6], oxygen doping in the organic semiconductor [7,8], charge trapping at the interface state or inside the insulator [9,10], water vapors in the insulator [10], bipolaron formation by accumulated holes [11], leakage current through the gate dielectric [12] and so on. On the other hand, it has been reported that the OTFTs exposed to atmosphere and/or prolonged stressing of gate bias will result in the performance degradation of pentacene-based OTFT in terms of field effect reduction, threshold voltage and subthreshold slope variation [4,13]. However, in our knowledge, the drain bias dependence on the electrical characteristics stability of pentacene-based OTFT has never been reported. Thus, in this study, we investigated the stability of pentacene-based OTFT under dc drain bias stress, especially in threshold voltage shift.

2. Experimental

The bottom-contact (BC) configuration of pentacene-based OTFTs were fabricated onto a highly doped n-type Si wafer (resistivity < 0.020 ohm-cm, 500 μ m-thick) acting as the gate electrodes. The pentacene-based OTFT configuration is shown in Figure 1. Thermally grown 100 nm-thick SiO₂ was used as the gate insulator and the Cr/Pt (2 nm/70 nm) were evaporated using an Electron-Beam evaporation system as Source/Drain (S/D) electrodes. The lift-off method was used to pattern the electrodes onto the SiO₂ and then the pentacene was deposited onto the SiO₂ as the active layer material. The substrate temperature was kept at 70 °C. Pentacene film at a thickness of 100 nm was deposited at a rate of 0.1 ~ 0.3 Å/s. The device's channel width (W) and channel length (L) were around 200 μ m and 50 μ m, respectively. The electrical measurement was performed using an Agilent HP 4156A semiconductor pa-

rameter analyzer in the dark and atmosphere at room temperature.

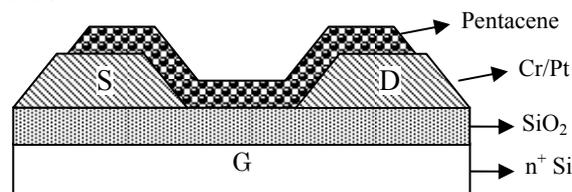


Fig. 1 Schematic diagram of pentacene-based OTFTs with bottom-contact configuration.

3. Results and Discussion

Fig. 2 shows the change in the typical transfer curves of pentacene-based OTFTs under storing in the atmosphere for a period time. After 1 hr exposure to ambient air, it is obvious that the on-current (I_{ON}) decreased from 2.51×10^{-6} A, off-current (I_{OFF}) increased from 2.20×10^{-12} to 4.26×10^{-12} A, and threshold voltage (V_{th}) increased from -2.5 to -21 V. The V_{th} was calculated from the plot of $I_{DS}^{1/2}$ against V_{GS} . The dependence of V_{th} and exposure time to ambient air is inserted in the Fig. 2. We believed that the O₂ and H₂O was adsorbed by pentacene film and filled the crevices between the pentacene grains, increasing the concentration of traps, resulting in the increased V_{th} and thus the performance degradation of pentacene-based OTFTs [5-8].

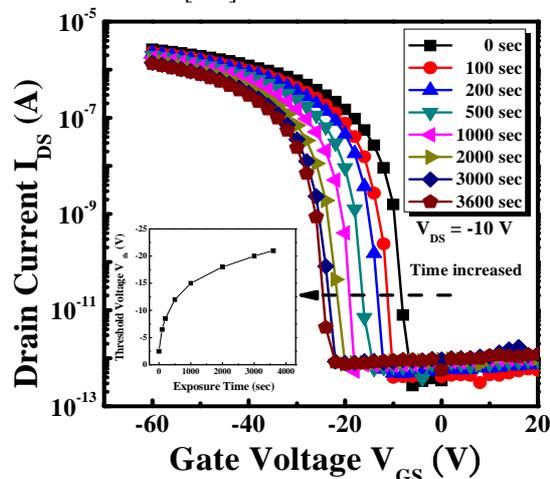


Fig. 2 Typical transfer curves (I_{DS} - V_{GS}) variations during 1 hr for the pentacene-based OTFTs exposure to ambient air. The inset shows the dependence of V_{th} of the device on exposure time (sec).

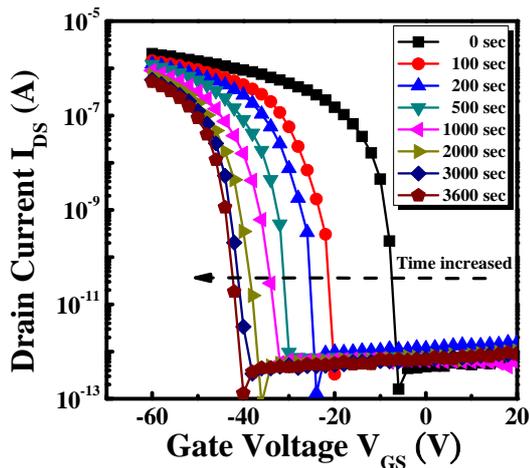


Fig. 3 Typical transfer curves (I_{DS} - V_{GS}) variations during 1 hr for the pentacene-based OTFTs under drain bias stress at $V_{DS} = 30$ V in atmosphere.

Fig. 3 shows the change in typical transfer curves of pentacene-based OTFTs stressed at $V_{DS} = 30$ V in atmosphere. It is obvious that the I_{ON} decreased from 2.05×10^{-6} to 5.23×10^{-7} A and V_{th} increased from -11 to -28 V. The Fig. 4 shows the different drain bias voltage as a function of stress time, stressed at $V_{DS} = 30$ V in atmosphere. It indicates that the drain bias was applied in positive or negative bias voltage and the V_{th} degradation is less than that applied in positive bias voltage. We believe that the increasing trap state density due to the adsorption of O_2 and H_2O in the pentacene film and the enhancement of vertical electrical-field are the main reasons. The pentacene is a p-type organic semiconductor and the pentacene-based OTFTs are usually operated in accumulation mode at $V_{GS} < 0$ and $V_{DS} < 0$. Thus, when V_{DS} was applied in positive bias voltage, the width of depletion region in the channel will be increased, resulting in the increased the traps density near drain side in the channel as a result of the adsorbed O_2 and H_2O in the pentacene film. On the other hand, the positive drain bias voltage will result in the vertical electric field in the channel larger than that in negative drain bias voltage. Thus, the carrier injection into gate insulator by the increased trap-state density due to the absorption of the O_2 and H_2O molecules will be enhanced with the effect of the large vertical electric field. The carrier injection into the gate insulator will result in the increasing extra oxide charges or interface states, existing in the gate insulator or at the interface between gate insulator and channel. Thus, the performances of pentacene-based OTFTs were significantly degraded, especially in the V_{th} .

4. Conclusions

The electrical characteristics of pentacene-based OTFTs in atmosphere and drain bias stress were investigated. The pentacene-based OTFTs under atmosphere stress was indicated that the I_{ON} from 2.51×10^{-6} to 1.33×10^{-6} A, I_{OFF} increased from 2.20×10^{-12} to 4.26×10^{-12} A, and V_{th} increased from -2.5 to -21 V. In addition, the pentacene-based OTFTs under drain bias stress caused large V_{th}

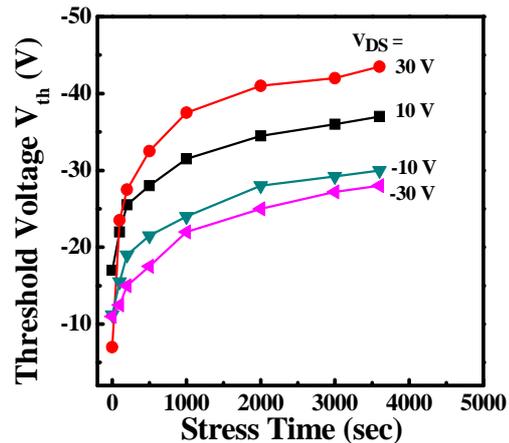


Fig. 4 Threshold voltage (V_{th}) variations as a function of stress time at different V_{DS} .

degradation. The V_{th} increased from -11 to -28 V. We presume that the carrier accumulated and increased the traps density near drain side in the channel and vertical electric field were the mainly factors for the V_{th} degradation.

Acknowledgements

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